Special Issue

State-of-the-Art 3D Imaging, Processing and Display Technologies

Message from the Guest Editors

Three-dimensional technologies have become an integral part of today's fundamental applications in immersive media, augmented reality, virtual reality, extended reality, games and entertainment, security, autonomous vehicles, and robotics, as well as in various enhancements of computer vision. This Special Issue covers selected outcomes of state-of-the-art research, ranging from 3D acquisition to its processing and applications. This Special Issue also serves as a comprehensive review on state-of-the-art 3D imaging techniques, their processing and display, and provides a broad insight into the development of various disciplines.

Guest Editors

Dr. Rafiq Swash
Prof. Dr. Anil Fernando
Prof. Dr. Hongying Meng

Deadline for manuscript submissions

20 October 2026

Applied Sciences

an Open Access Journal by MDPI

Impact Factor 2.5
CiteScore 5.5

mdpi.com/si/218733

Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
applsci@mdpi.com

mdpi.com/journal/applsci

MDPI

Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.5

mdpi.com/journal/applsci

About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

Author Benefits

Open Access:

free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:

indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, Embase, CAPlus / SciFinder, and other databases.

Journal Rank:

JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)